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LEOC	O CORPORATION	PRODUCTION SPECIFICATION	No. S-04-5011 Rev. 5							
* 5011 Series RAST 5 connector *										
This product specification contains the test method, the following datum are the general										
performance and requirements of the LEOCO 5011 series wafer & socket.										
1. Construction and dimensions shall be in accordance with the referenced drawings.										
2. Characteristics:										
Curr	ent rating: 16 A max.	AC DC								
Volta	age rating: 380V A	C DC								
Tem	perature rating: -40°C	℃ ~ +120 ℃								
3. Elec	trical performance:		_							
Item	Description	Test Method & Condition	Requirement							
3-1	Contact resistance	It should be tested in accordance with	20m Ω max. Initial.							
		method EIA-364-23.	After test 40 m Ω max.							
3-2	Insulation resistance	In accordance with EIA-364-21, DC 500 V	1000 M Ω min.							
		shall be applied between contacts and								
		between an individual contact and a case								
		for one minute.								
3-3 Dielectric		In accordance with EIA-364-20, AC 500 V	There should be not flash							
	Withstanding	shall be applied between contacts and over spark over o								
	Voltage	between an individual contact and a case	dielectric breakdown.							
		for one minute.								
		(leak current 2mA)								
4. Mech	anical Performance :									
ltem	Description	Test Method & Condition	Requirement							
4-1	Pin Retention Force	Apply axial pull out force at the speed: 25	4.0kgf/Contact Min.							
	from Base	mm / minute on the contact assembled in								
		the housing.								
4-2	Terminal Retention	Apply axial pull out force at the speed: 25	4.0kgf/Contact Min.							
	Force from Housing	mm / minute on the contact assembled in								
		the housing.								
4-3	Durability	It should be tested in accordance with	Contact resistance less							
4-0		method EIA-364-09.	than twice of initial.							
		Connector shall be subjected to 10 cycles								
		of insertion and withdrawal in one minute.								

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5. Envir	onmental Performance	:	i			
Item	Description	Test Method & Condition	Requirement			
5-1	Humidity	Test method EIA-364-31.	NO damage. Contact resistance less than			
		Temperature: 40±2 °C				
		Humidity: 90 ~ 95 % (RH)	twice			
		Period: 96 hours.	Insulation resistance more than 10 $M\Omega$			
5-2	Salt Spray			damage.		
		with method EIA-364-26.	Contact resistance less th			
		Temperature: 35±2 ° C	twice	e of initial.		
		Density: 5 % in weight.				
F 0	O - Lele a - Lellite -	Period: 48 hours.				
5-3	Solder ability	Connector termination ends shall be		damage.		
		checked for solder ability in accordance with method EIA-364-52.		mum: 95 % of i	mmersec	
		Solder temperature: 260 ± 5 ° C	area			
		Immersion period: 5 ± 0.5 sec.				
5-4	Temperature rise	Mate connectors: Measure the	Tem	perature rise 5	0°C	
		temperature rise at rated current after 4	max			
		hours.				
		Test method: EIA-364-70				
5-5	Heat aging	Temperature:85±2℃	No d	amage.		
		Period:96 hours	Contact resistance less than			
			twice of initial.			
5-6	Resistance to	Soldering temperature: 260±5°C	No d	amage.		
	Soldering Heat	Soldering time:3~5 sec.	Contact resistance less than			
			twice of initial.			
5-7	Low temperature	Temperature:-25±3℃		amage.		
		Period:96 hours		act resistance	less than	
			twice	e of initial.		
	test item	- - - - - - - - - -	 .	,	. ,	
6-1	U	Test shall be according to test 4a of		e shall be not f		
	of IEC 60512)	IEC60512.Test duration shall be 1 min.				
		Test voltage is 1.39KV (rms)	prea	Kaown.		

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7.Product Qualification Test	Sequenc	e			·			<u>.</u>	
Test or Examination		1	2	3	4		5	6	
		Test Sequence							
Appearance examinati					6		1, 3		
product	1	1,7	1, 8	1,	6	1	1, 3		
Contact resistance			2, 8	2, 9		2			
Insulation resistance			3	3	:	3			
Dielectric Withstanding Voltage		4	4		4				
Pin Retention Force from Base	2								
Terminal Retention Force from I	3								
Humidity			5						
Heat aging				5					
Salt Spray					5				
Solder ability				6					
Temperature rise							2		
Durability		4							
Resistance to Soldering Heat				7					
Low temperature		6							
Voltage proof(Test 4a of IEC 60							2		
8. Socket Mating Force and I	Jnmating	g Force	for RA	ST 5 Seria	al:				
(Without lock on the Housin	ng)			1					
No. Of circuits Mating	Mating Force Max. (Unit: kgf) 4.0			Unmating Force Min. (Unit: kgf)					
2 Circuits				1.6					
3 Circuits	5.0)			2.2				
4 Circuits	6.0			2.8					
5 Circuits			3.4						
6 Circuits			4.0						
9. Socket Mating Force and I (With lock on the Housing)	Jnmatinę	g Force	for RA	ST 5 Seria	al:				
No. Of circuits Mating	Mating Force Max. (Unit: kgf)			Unmating Force Min. (Unit: kgf)					
2 Circuits	4.5			2.6					
3 Circuits	5.5			3.2					
4 Circuits	9.0			3.8					
5 Circuits	10.5			4.4					
6 Circuits	12.0			5.0					
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